Radiation Report SN54SC2T74-SEP Single-Event Effects (SEE) Radiation Report



ABSTRACT

The purpose of this study is to characterize the single-event-effects (SEE) performance due to heavy-ion irradiation of the SN54SC2T74-SEP. SEE performance was verified at minimum (1.2V) and maximum (5.5V) operating conditions. Heavy-ions with an LET_{EFF} of 43MeV-cm²/ mg were used to irradiate three production devices with a fluence of 1 × 10⁷ ions / cm². The results demonstrate that the SN54SC2T74-SEP is SEL-free up to LET_{EFF} = 43MeV-cm² / mg as 125°C. SET performance for minimum and maximum operating voltages saw no excursions ≥ |1%|, as shown and discussed in this report.

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1 Overview

The SN54SC2T74-SEP is a radiation-tolerant, 1.2V to 5.5V dual D-type flip-flop with integrated translation. The input is designed with a lower threshold circuit to support up translation for lower voltage CMOS inputs (for example, 1.2V input to 1.8V output or 1.8V input to 3.3V output). In addition, the 5V tolerant input pins enable down translation (for example, 3.3V to 2.5V output).

For more information, see the SN54SC2T74-SEP product page.

Table 1-1. Overview Information

Description	Device Information		
TI Part Number	SN54SC2T74-SEP		
MLS Number	SN54SC2T74MPWTSEP		
Device Function	Radiation-tolerant, 1.2V to 5.5V, dual D-type flip-flop with integrated translation		
Technology	LBC9		
Exposure Facility	Radiation Effects Facility, Cyclotron Institute, Texas A&M University		
Heavy Ion Fluence per Run	1 × 10 ⁷ ions / cm ²		
Irradiation Temperature	25°C (for SET testing) and 125°C (for SEL testing)		



2 Single-Event Effects (SEE)

The primary single-event effect (SEE) event of interest in the SN54SC2T74-SEP is the destructive single-event latch-up. From a risk or impact perspective, the occurrence of an SEL is potentially the most destructive SEE event and the biggest concern for space applications. In mixed technologies such as the Linear BiCMOS (LBC9) process used for SN54SC2T74-SEP, the CMOS circuitry introduces a potential SEL susceptibility. SEL can occur if excess current injection caused by the passage of an energetic ion is high enough to trigger the formation of a parasitic cross-coupled PNP and NPN bipolar structure (formed between the p-substrate and n-well and n+ and p+ contacts). The parasitic bipolar structure initiated by a single-event creates a high-conductance path (inducing a steady-state current that is typically orders-of-magnitude higher than the normal operating current) between power and ground that persists (is latched) until power is removed or until the device is destroyed by the high-current state. The process modifications applied for SEL-mitigation were sufficient, as the SN54SC2T74-SEP exhibited no SEL with heavy-ions up to an LET_{EFF} of 43 MeV-cm² / mg at a fluence of 1 × 10⁷ ions / cm² and a chip temperature of 125°C.



Figure 2-1. Functional Block Diagram of the SN54SC2T74-SEP



3 Test Device and Test Board Information

The SN54SC2T74-SEP is a packaged 14-pin, TSSOP plastic package shown in the pinout diagram in Figure 3-1. Figure 3-2 shows the device with the package cap decapped to reveal the die for heavy ion testing. Figure 3-3 shows the evaluation board used for radiation testing. Figure 3-4 shows the bias diagram used for Single-Event Latch-up (SEL) testing. Figure 3-5 shows the bias diagram used for Single-Event Transient (SET) testing.



Figure 3-1. SN54SC2T74-SEP Pinout Diagram



Figure 3-2. Photo of SN54SC2T74-SEP Package Decapped



Figure 3-3. SN54SC2T74-SEP Evaluation Board (Top View)





Figure 3-4. SN54SC2T74-SEP SEL Bias Diagram

Figure 3-5. SN54SC2T74-SEP SET Bias Diagram



Figure 3-6. SN54SC2T74-SEP Thermal Image for SEL

4 Irradiation Facility and Setup

The heavy-ion species used for the SEE studies on this product were provided and delivered by the Texas A&M University (TAMU) Cyclotron Radiation Effects Facility using a superconducting cyclotron and an advanced electron cyclotron resonance (ECR) ion source. At the fluxes used, the ion beams had good flux stability and high irradiation uniformity over a one inch diameter circular cross-sectional area for the in-air station. Uniformity is achieved by magnetic defocusing. The flux of the beam is regulated over a broad range spanning several orders of magnitude. For the majority of these studies, ion flux of 1×10^5 ions / cm²-s were used to provide heavy-ion fluences of approximately 1×10^7 ions / cm². Ion uniformity for these experiments was between 95% and 98%.

Figure 4-1 shows one of the three SN54SC2T74-SEP test board used for experiments at the TAMU facility. The in-air gap between the device and the ion beam port window was maintained at 40mm for all runs.



Figure 4-1. SN54SC2T74-SEP Evaluation Board at the TAMU Facility

5 Results 5.1 SEL Results

During SEL characterization, the device was heated using forced hot air, maintaining device temperature at 125°C. A FLIR (FLIR ONE Pro LT) thermal camera was used to validate die temperature to make sure the device was accurately heated (see SN54SC2T74-SEP Thermal Image for SEL.) The species used for SEL testing was a Silver (¹⁰⁹Ag) ion at 15MeV / μ with an angle-of-incidence of 0° for an LET_{EFF} of 43MeV-cm²/ mg. A fluence of approximately 1 × 10⁷ ions / cm² was used for the runs.

The three devices were powered up and exposed to the heavy-ions using the maximum recommended supply voltage of 5.5V using a National Instruments[™] PXI Chassis PXIe-4139 and a 5V, 1MHz square wave input using a Tektronix[®] AFG3102 function generator. The run duration to achieve this fluence was approximately 90 seconds. As listed in Table 5-1, no SEL events were observed during the nine runs, indicating that the SN54SC2T74-SEP is SEL-free. Figure 5-1, Figure 5-2, and Figure 5-3 show the plots of current versus time for runs one, four, and seven, respectively.

Run Number	Unit Number	Distance (mm)	Temperature (°C)	lon	Angle	Flux (ions × cm ² / mg)	Fluence (Number of ions)	LET _{EFF} (MeV × cm ² /mg)	Did an SEL event occur?
1	1	40	124	Ag	0°	1.00E+05	1.00E+07	43	No
2	1	40	124	Ag	0°	1.00E+05	1.00E+07	43	No
3	1	40	124	Ag	0°	1.00E+05	1.00E+07	43	No
4	2	40	123	Ag	0°	1.00E+05	1.00E+07	43	No
5	2	40	123	Ag	0°	1.00E+05	1.00E+07	43	No
6	2	40	123	Ag	0°	1.00E+05	1.00E+07	43	No
7	3	40	124	Ag	0°	1.00E+05	1.00E+07	43	No
8	3	40	124	Ag	0°	1.00E+05	1.00E+07	43	No
9	3	40	124	Ag	0°	1.00E+05	1.00E+07	43	No

Table 5-1. Summary of SN54SC2T74-SEP SEL Test Conditions and Results



Figure 5-1. Current versus Time for Run 1 of the SN54SC2T74-SEP at T = 125°C



Figure 5-2. Current versus Time for Run 4 of the SN54SC2T74-SEP at T = 125°C



Figure 5-3. Current versus Time for Run 7 of the SN54SC2T74-SEP at T = 125°C

No SEL events were observed, indicating that the SN54SC2T74-SEP is SEL-immune at LET_{EFF} = 43MeV- cm^2 / mg and T = 125°C. Using the MFTF method shown in Single-Event Effects (SEE) Confidence Internal Calculations, the upper-bound cross-section (using a 95% confidence level) is calculated as:

 $\sigma_{\text{SEL}} \le 1.23 \times 10^{-7} \text{ cm}^2/\text{device for LET}_{\text{EFF}} = 43 \text{ MeV} \cdot \text{cm}^2/\text{mg and T} = 125^{\circ}\text{C}$ (1)



5.2 Single-Event Transients (SET)

SETs are defined as heavy-ion-induced transient upsets on output pin 1Q of the SN54SC2T74-SEP. SET testing was performed at room temperature (no external temperature control applied). The species used for the SET testing was ¹⁰⁹Ag for a LET_{EFF} = 48MeV × cm² / mg. Flux of approximately 10⁵ ions / cm² × s and a fluence of approximately 10⁷ ions / cm² were used for the SET runs.

Three units were tested across multiple input conditions to determine the worst-case setup for SETs. The unit was tested with V_{CC} of 1.2V, 1.8V, and 5.5V and window trigger of ±1%, ±5%, ±10%, and ±20%. All combinations of V_{CC} and window triggers showed no transient upsets, as listed in Table 5-2

To capture SETs, one NI PXI-5110 scope card was used to continuously monitor the output voltage on pin 1Q. The NI scope was programmed to a sample rate of 100M samples per second (S / s) and recorded 10k samples, with a 20% pretrigger reference, in case of an event (trigger). Under heavy-ions, the SN54SC2T74-SEP did not exhibit any transient upsets

Run Number	Unit Number	lon	LET _{EFF} (MeV × cm ² /mg)	FLUX (ions × cm²/ mg)	Fluence (Number ions)	Window Trigger	SET Upsets
21	1	¹⁰⁹ Ag	48	1.05 × 10 ⁵	9.98 × 10 ⁶	20%	0
22	1	¹⁰⁹ Ag	48	1.07 × 10 ⁵	1.00 × 10 ⁷	20%	0
23	1	¹⁰⁹ Ag	48	1.05 × 10 ⁵	1.00 × 10 ⁷	20%	0
24	1	¹⁰⁹ Ag	48	1.08 × 10 ⁵	9.95× 10 ⁶	10%	0
25	2	¹⁰⁹ Ag	48	1.06 × 10 ⁵	1.00 × 10 ⁷	20%	0
26	2	¹⁰⁹ Ag	48	1.04 × 10 ⁵	1.00 × 10 ⁷	20%	0
27	2	¹⁰⁹ Ag	48	1.01 × 10 ⁵	1.00 × 10 ⁷	20%	0
28	2	¹⁰⁹ Ag	48	1.18 × 10 ⁵	9.96 × 10 ⁶	20%	0
29	2	¹⁰⁹ Ag	48	1.14 × 10 ⁵	9.98 × 10 ⁶	20%	0
30	2	¹⁰⁹ Ag	48	1.19 × 10 ⁵	1.00 × 10 ⁷	20%	0
31	3	¹⁰⁹ Ag	48	1.23 × 10 ⁵	9.95 × 10 ⁶	20%	0
32	3	¹⁰⁹ Ag	48	1.22 × 10 ⁵	9.98 × 10 ⁶	20%	0
33	3	¹⁰⁹ Ag	48	1.23 × 10 ⁵	9.95 × 10 ⁶	20%	0
34	3	¹⁰⁹ Ag	48	1.27 × 10 ⁵	1.00 × 10 ⁷	20%	0
35	3	¹⁰⁹ Ag	48	1.23 × 10 ⁵	1.00 × 10 ⁷	20%	0
36	3	¹⁰⁹ Ag	48	1.17 × 10 ⁵	1.00 × 10 ⁷	20%	0
37	3	¹⁰⁹ Ag	48	1.16 × 10 ⁵	9.98 × 10 ⁶	5%	0
38	3	¹⁰⁹ Ag	48	1.18 × 10 ⁵	9.96 × 10 ⁶	1%	0
40	3	¹⁰⁹ Ag	48	1.10 × 10 ⁵	9.94 × 10 ⁶	1%	0

Table 5-2. Summary of SN54SC2T74-SEP SET Test Condition and Results

5.3 Event Rate Calculations

Event rates were calculated for LEO (ISS) and GEO environments by combining CREME96 orbital integral flux estimations and simplified SEE cross-sections according to methods shown in *Heavy Ion Orbital Environment Single-Event Effects Estimations*. A minimum shielding configuration of 100mils (2.54mm) of aluminum, and *worst-week* solar activity is assumed. (This is similar to a 99% upper bound for the environment.) Using the 95% upper-bounds for the SEL and the SET, the event rate calculation for the SEL and the SET is listed in Table 5-3 and Table 5-4, respectively. Note that this number is for reference since no SEL or SET events were observed.

Table 3-3. SEE Event Nate Calculations for Worst-Week EEO and GEO Orbits							
Orbit Type	Onset LET _{EFF} (MeV-cm ² / mg)	CREME96 Integral FLUX (per day / cm ²)	σSAT (cm²)	Event Rate (per day)	Event Rate (FIT)	MTBE (Years)	
LEO (ISS)	48	6.40 × 10 ⁻⁴	1.23 × 10 ⁻⁷	7.87 × 10 ⁻¹¹	3.28 × 10 ⁻³	3.48 × 10 ⁷	
GEO	40	2.17 × 10 ⁻³	1.25 ~ 10	2.67 × 10 ⁻¹⁰	1.11 × 10 ⁻²	1.03 × 10 ⁷	

Table 5-3. SEL Event Rate Calculations for Worst-Week LEO and GEO Orbits

Table 5-4. SET Event Rate (Calculations for	Worst-Week LEC) and GEO Orbits
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Orbit Type	Onset LET _{EFF} (MeV-cm ² / mg)	CREME96 Integral FLUX (per day / cm ²)	σSAT (cm²)	Event Rate (per day)	Event Rate (FIT)	MTBE (Years)
LEO (ISS)	48	6.40 × 10 ⁻⁴	1.94 × 10 ⁻⁸	1.24 × 10 ⁻¹¹	5.16 × 10 ⁻⁴	2.21 × 10 ⁸
GEO	40	2.17 × 10 ⁻³	1.94 ~ 10	4.20 × 10 ⁻¹¹	1.75 × 10 ^{−3}	6.52 × 10 ⁷

MTBE is the mean-time-between-events in years at the given event rates. These rates clearly demonstrate the SEE robustness of the SN54SC2T74-SEP in two harshly conservative space environments. Customers using the SN54SC2T74-SEP must only use the above estimations as a rough guide and TI recommends performing event rate calculations based on specific mission orbital and shielding parameters to determine if the product satisfies the reliability requirements for the specific mission.



6 Summary

The purpose of this study was to characterize the effects of heavy-ion irradiation on the single-event latch-up (SEL) performance of the SN54SC2T74-SEP radiation-tolerant, 1.2V to 5.5V dual D-type flip-flop with integrated translation. SEE performance was verified at minimum (1.2V) and maximum (5.5V) operating conditions. Heavy-ions with an LET_{EFF} of 43MeV-cm²/ mg were used to irradiate three production devices with a fluence of 1×10^7 ions / cm². The results demonstrate that the SN54SC2T74-SEP is SEL-free up to LET_{EFF} = 43MeV-cm²/ mg as 125°C. SET performance for minimum and maximum operating voltages saw no excursions ≥ |1%|, as shown and discussed in this report.



7 References

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